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**High Strength Ambient Curable
 Two Components or Pre-mixed Frozen
 Electrically Conductive
 Epoxy Paste Adhesive**

IDEAL FOR:

- Die Attach
- Substrate Attach (Matched CTE's)
- Ambient Curing

DESCRIPTION:

EG8020 is a two-part, silver filled, room temperature curable adhesive upon mixing. This paste has good bond strength and is both electrically and thermally conductive.

The easy mix ratio of 1:1 by weight or volume and ambient curable with long pot-life enable the adhesive to be used for small volume field and larger volume production applications.

AVAILABILITY:

EG8020 is available in syringes for automatic needle dispense applications or in jars. Both viscosity and thixotropic index can be modified to your specific needs. It can be premixed and frozen.

APPLICATION PROCEDURES:

- (1) Mix adhesive in 1:1 weight ratio. (Note: In kit form, Part A viscosity > Part B viscosity).
- (2) Dispense adhesive onto clean substrate.
- (3) Cure according to one of the recommended schedules.

CAUTION: This product may cause skin irritation. Avoid skin contact. If contact does occur, wash immediately with soap and water. Please refer SDS for more details.

The information contained herein is believed to be reliable. All recommendations or suggestions are made without guarantee inasmuch as conditions and methods of commercial use are beyond our control. Properties given are typical values and not intended for use in preparing specifications. The user is advised to evaluate the product in the manner the product is to be used in manufacturing and in the final product. Under no circumstance shall AI Technology be liable for accidental, consequential or other damages arising from the use or handling of this product.

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**PRIMA-BOND
 EG8020**

TYPICAL PROPERTIES*

Electrical Resistivity (150 °C/ 60 minutes)	<4x10⁻⁴ ohm-cm
Dielectric Strength (Volts/mil)	N/A
Glass Transition Temp.(°C)	50 ±10%
Current Carrying Capabilities	> 40 Amp/mm²
Lap-Shear Strength	>900 psi >6.2 N/mm²
Device Push-off Strength	>1800 psi >12.4 N/mm²
Cured Density (gm/cc)	3.5 ±10%
Thermal Conductivity	40 Btu-in/hr-ft²-°F ±10% 5.7 W/m-°C ±10%
Linear Thermal Expansion Coeff. (ppm/°C)	40
Maximum Continuous Operation Temp. (°C)	<150
Avg. Viscosity(0.5 rpm, 25°C) (Brookfield DV-1, spindle CP51)	150,000 cp ±20%

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CURE SCHEDULES:

Temperature	Time
25°C	168 hr
60°C	32 hr
80°C	16 hr
100°C	5 hr
125°C	3 hr

If premixed and frozen version is used, thaw for 30 minutes and cure according to one of the recommended schedules.

**Shelf life is for unmixed components. If premixed: -40°C for 6 months. Pot life is 4 hours at 25°C, after mixing.

SHELF LIFE:

Storage temperature	Shelf Life
**25°C	1 yr